

NP/NPE free (meet REACH requirement) 不含壬基酚（符合歐盟REACH環保規範）

NP (Nonyl Phenol) / NPE (Nonyl Phenol Ethoxylate) are generally used as surfactant. However, due to health and environmental hazards, NP/NPE has been banned in EU.

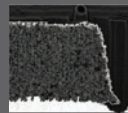
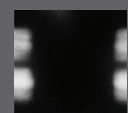
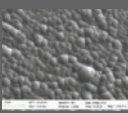
壬基酚一般用作界面活性劑。然而基於對健康及環境的危害，壬基酚已被歐盟禁止使用。

Product 產品	Features and Benefits 特性及效益	
RONACLEAN™ EVP 200 Cleaner Series	<ul style="list-style-type: none"> One component acid cleaner 單一成份酸性清潔劑 Excellent cleaning performance for dry film and other residues 針對乾膜及其他殘渣，具有絕佳的清潔能力 Capable of pattern process without damaging dry film 適用於線路鍍銅製程，同時並不會損害乾膜。 	 <p>Excellent detergency without damaging dry film 絕佳的清潔能力，且不會損害乾膜。</p>
RONASTAN™ ECX Tin Plating	<ul style="list-style-type: none"> Cost Effective 成本效益優勢 Environmentally-friendly 環保導向 Higher alkaline etching resistance 高抗鹼性能力 Robustness to organic contamination 有機屋留具有高容忍度 	 <p>Excellent coverage and resistance 絕佳的鍍層覆蓋及抗蝕刻能力</p>
CRIMSON™ Sensitizer 5123M-1	<ul style="list-style-type: none"> Excellent and uniform coverage on both glass fiber and resin 在玻璃纖維及樹脂上，皆有絕佳且一致的覆蓋性 Provide optimum Pd adsorption for all laminate and dielectric materials yielding complete electroless copper coverage 在不同板上，提供最適化支鉑吸附量，助於化學沉銅產生完整的覆蓋 Excellent reliability performance 絕佳的信賴度表現 	 <p>Excellent coverage and reliability performance 絕佳的覆蓋性及信賴度表現</p>
CIRCUPOSIT™ Conditioner 3323A		

EDTA free 不含乙二酸四乙胺

EDTA (Ethylenediaminetetraacetic acid) is a chelating agent. It captures abundant metal ions in solution but itself is not easy to be degraded, making it a persistent organic pollutant.

EDTA作為螯合劑。它於水溶液中捕捉大量金屬離子但本身卻不易被分解，使其成為長期有機汙染物

Product 產品	Features and Benefits 特性及效益	
CIRCUPOSIT™ ADV 8550 Electroless Copper	<ul style="list-style-type: none"> High speed deposition with excellent bath stability 沉積速率快且槽液穩定性亦高 Pure Copper metal deposition without affect to for Flash etching speed 純銅金屬沉積，不影響後段線路蝕刻速率 	 <p>Excellent Plating uniformity on Microvia 在盲孔內，具有優良的沉積均勻度</p>
CIRCUPOSIT™ 328 Electroless Copper	<ul style="list-style-type: none"> High-yield, "thin" electroless copper, tartrate-based 高附載，薄化學沉銅，酒石酸系統 Excellent plating coverage and copper-to-copper bonds achieved with all electroplate coppers 絕佳的化學銅鍍層覆蓋性，使其與不同的電鍍銅，皆可達成良好的銅與銅連結力 	 <p>Excellent coverage on PI 在PI上具有絕佳的覆蓋能力</p>
AUROLECTROLESS™ SMT 525G	<ul style="list-style-type: none"> Low gold content operation with 0.5-1.0g/L 低金含量操作，金濃度為 0.5-1.0g/L Low gold porosity deposition with very good Ni coverage to avoid corrosion in post treatment process 低疏孔性的化學金層，良好解且致密地覆蓋於鍍層之上，可避免後製程的腐蝕及攻擊。 Compatible with ENEPIG and Selective ENIG process 適用於化學鍍金及選擇性化學鍍金製程 	 <p>No Ni corrosion 無鍍層腐蝕</p>

Formaldehyde free/ HCHO free 不含甲醛

Formaldehyde is a strong reducing agent. Nonetheless, it causes health damage by inhalation.

甲醛為一強還原劑。不過經由吸入會對人體造成健康危害。

Product 產品	Features and Benefits 特性及效益
CRIMSON™ Direct Plating	The leading palladium-based direct plate system in horizontal process that creates a stable sulfide conversion coating 硫化鉑系統的直接電鍍製程，適用於水平線，並可產生穩定鍍層
CONDUCTRON™ Direct Plating	Unique palladium-based system that creates the conductive direct plate coating with fine quality and high reliability 獨特的鉑系統直接電鍍製程，可產生良好品質及高信賴度的鍍層